

General Description

The Sanrise SRT10N070H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT10N070H break down voltage is 100V and it has a high rugged avalanche characteristics. The SRT10N070H is available in PDFN5*6 and TO-220C packages.

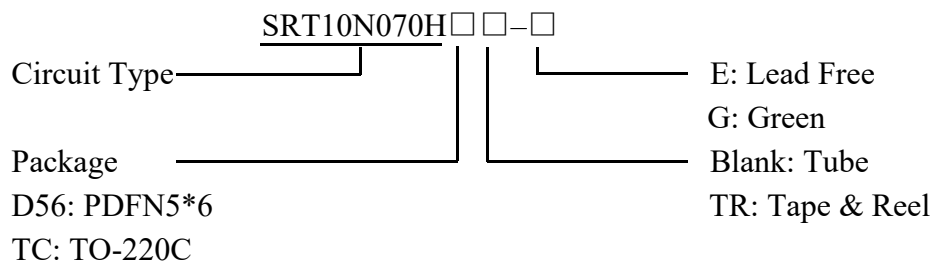
Features

- Ultra Low
- $R_{DS(ON_TYP)} = 5.7m\Omega$,PDFN5*6 @ $V_{GS} = 10V$.
- $R_{DS(ON_TYP)} = 6.3m\Omega$,TO-220C @ $V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g=32.1nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- Charger / Adapter
- Server/Telecom
- High Power Supply
- E-Tools

Ordering Information



Package	Part Number	Marking ID	Packing Type
PDFN5*6	SRT10N070HD56TR-G	SRT10N070HD56G	Tape & Reel
TO-220C	SRT10N070HTC-G	SRT10N070HTCG	Tube

Symbol

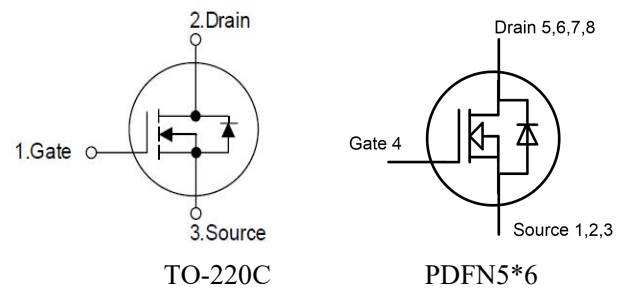


Figure 1 Symbol of SRT10N070H

Package Type

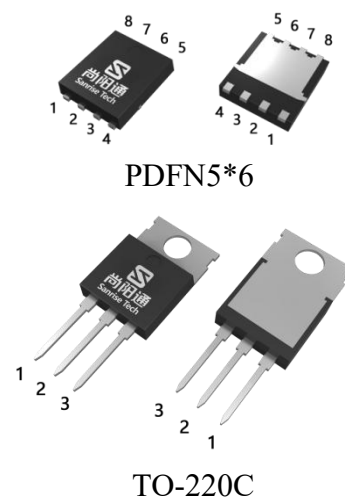


Figure 2 Package Type of SRT10N070H

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		V_{DSS}	100	V	
Gate-Source Voltage		V_{GSS}	±20	V	
Continuous Drain Current	$T_C=25^{\circ}\text{C}$	I_D	PDFN5*6	84	A
			TO-220C	87	
	$T_C=100^{\circ}\text{C}$		PDFN5*6	53	
			TO-220C	56	
Pulsed Drain Current (Note 2)		I_{DM}	336	A	
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	36	mJ	
Avalanche Destructive Energy, Single Pulse (Note 4)		E_{AS_Limit}	306	mJ	
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.05	mJ	
Avalanche Current, Repetitive (Note 2)		I_{AR}	12	A	
Continuous Diode Forward Current		I_S	84	A	
Diode Pulse Current		$I_{S,PULSE}$	320	A	
Max Power Dissipation		P_D	96.1	W	
Operating Junction Temperature		T_J	150	°C	
Storage Temperature		T_{STG}	-55 to 150	°C	
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	°C	

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS}=12.0\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
- $I_{AS_Limit}=35\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			1.3	°C/W
Thermal Resistance, Junction-to-Ambient		R_{thJA}			50	°C/W
Thermal Resistance, Junction-to-Case	TO-220C	R_{thJC}			1.1	°C/W
Thermal Resistance, Junction-to-Ambient		R_{thJA}			60	°C/W

Electrical Characteristics

 T_J = 25 °C, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	100			V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	uA	
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =20V, V _{DS} =0V		100	nA	
	Reverse	I _{GSSR}	V _{GS} =-20V, V _{DS} =0V		-100		
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =0.25mA	2.0	3.0	4.0	V	
Static Drain-Source On-Resistance	PDFN5*6	R _{DSS(ON)}	V _{GS} =10V, I _D =14A		5.7	7.0	mΩ
	TO-220C				6.3	7.5	
Gate Resistance	R _G	f=1MHz, Open Drain		1.7		Ω	
Dynamic Characteristics							
Input Capacitance	C _{ISS}	V _{DS} =50V, V _{GS} =0V, f=1MHz		2.1		nF	
Output Capacitance	C _{OSS}			720		pF	
Reverse Transfer Capacitance	C _{RSS}			13		pF	
Effective output capacitance, energy related ^{NOTE5}	C _{O(er)}	V _{GS} =0V, V _{DS} =0...80V		690		pF	
Effective output capacitance, time related ^{NOTE6}	C _{O(tr)}			920			
Turn-on Delay Time	t _{d(on)}	V _{DD} =50V, I _D =30A R _G =3.0Ω, V _{GS} =10V		10		nS	
Rise Time	t _r			5			
Turn-off Delay Time	t _{d(off)}			22			
Fall Time	t _f			6			
Gate Charge Characteristics							
Gate to Source Charge	Q _{gs}	V _{DD} =50V, I _D =30A V _{GS} =0 to 10.0V		9.7		nC	
Gate to Drain Charge	Q _{gd}			6.2			
Gate Charge Total	Q _g			32.1			
Gate Plateau Voltage	V _{plateau}			4.6		V	
Gate Charge Total, sync FET	Q _g	V _{DD} =0.1V, V _{GS} =0 to 10V		27.6		nC	
Reverse Diode Characteristics							
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _{SD} =30A		0.85	1.1	V	
Reverse Recovery Time	t _{rr}	V _R =50V, I _F =30A dI _F /dt=100A/us		53		nS	
Reverse Recovery Charge	Q _{rr}			93		nC	
Peak Reverse Recovery Current	I _{rrm}			3.5		A	

Note:

- C_{O(er)} is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 80V
- C_{O(tr)} is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80 V



Sanrise Technology Limited Company

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